

# Sylgard<sup>®</sup> 170 Silicone Elastomer

## **FEATURES**

- Low viscosity
- Room temp or heat accelerated cure
- Moderate thermal conductivity
- UL 94V-0 and
- Mil Spec tested to MIL-PRF-23586F (specifically listed material numbers only)

## **BENEFITS**

- Rapid, versatile cure processing controlled by temperature
- Low viscosity enhances flow and fill in narrow spaces and around complex geometries
- Can be considered for uses requiring added flame resistance and Mil Spec applications

## **COMPOSITION**

- Two-part
- 1 to 1 mix ratio
- Polydimethylsiloxane silicone elastomer

Two-part, 1 to 1 mix, black, general purpose encapsulant with good flowability and flame resistance

## **APPLICATIONS**

Suitable for general potting material for:

- Power supplies
- Connectors
- Sensors
- Industrial controls
- Transformers
- Amplifiers
- High voltage resistor packs
- Relays

## **TYPICAL PROPERTIES**

Specification Writers: These values are not intended for use in preparing specifications. Please contact your local Dow Corning sales office or your Global Dow Corning Connection before writing specifications on this product.

<b>Property</b>	<b>Unit</b>	<b>Result</b>
One or Two-Part	-	Two
Color (Part A)	-	Black
Viscosity (Part A)	cP Pa-sec	3,160 3.1
Viscosity (Part B)	cP Pa-sec	1,110 1.1
Viscosity (Mixed)	cP Pa-sec	2,135 2.1
Specific Gravity (Uncured Part A)	-	1.37
Specific Gravity (Uncured Part B)	-	1.37
Thermal Conductivity	btu/hr ft degf w/mK	0.277 0.48
Working Time at 25 °C (Pot Life - minutes)	minutes	282.6
Cure Time at 25 °C	hours	24
Heat Cure Time at 70 °C	minutes	25
Heat Cure Time at 100 °C	minutes	10
Durometer Shore A	-	46.82
Dielectric Strength	volts/mil kV/mm	472 18
Volume Resistivity	ohm *cm	6,336
Dielectric Constant at 2 Hz	-	2.7
Dielectric Constant at 5 Hz	-	2.67
Dissipation Factor at 2 Hz	-	0.0027
Dissipation Factor at 5 Hz	-	0.0006
Linear CTE (by TMA)	ppm/°C	275

## DESCRIPTION

*Dow Corning*<sup>®</sup> brand silicone encapsulants are supplied as two-part liquid component kits with a mixed ratio of 1 to 1. When liquid components are thoroughly mixed, the mixture cures to a flexible elastomer, which is well suited for the protection of electrical/electronic applications.

*Dow Corning* silicone encapsulants cure without exotherm at a constant rate regardless of sectional thickness or degree of confinement.

*Dow Corning* silicone encapsulants require no post cure and can be placed in service immediately following the completion of the cure schedule. Standard silicone encapsulants require a surface treatment with a primer in addition to good cleaning for adhesion while primerless silicone encapsulants require only good cleaning

This material has a UL 94 -V-0 flame rating. Please review UL file QMFZ2.E40195 for more specific information on the thickness ranges tested.

## APPLICATION METHODS

- Automated mixing and dispensing
- Manual mixing

## MIXING AND DE-AIRING

These products are supplied in a 1 to 1 mix ratio, which is very robust in manufacturing environments and allows for some process and dispense equipment variation. In most cases de-airing is not required.

## PREPARING SURFACES

In applications requiring adhesion, priming will be required for many of the silicone encapsulants. For best results, the primer should be applied in a very thin, uniform coating and then wiped off after application. After application, it should be thoroughly cured prior to application of the silicone elastomer. Additional instructions for primer usage can be found in the information sheets specific to the individual primers.

## PROCESSING/CURING

Thoroughly mixed *Dow Corning* silicone encapsulants may be poured/dispensed directly into the container in which it is to be cured. Care should be taken to minimize air entrapment. When practical, pouring/dispensing should be done under vacuum, particularly if the component being potted or encapsulated has many small voids. If this technique cannot be used, the unit should be evacuated after the silicone encapsulant has been poured/dispensed. *Dow Corning* silicone encapsulants may be either room temperature (25 °C/77 °F) or heat cured. Room temperature cure encapsulants may also be heat accelerated for faster cure. Ideal cure conditions for each product are given in the product selection table. Two-part condensation cure encapsulants should not be heat accelerated above 60 °C (140 °F).

## POT LIFE AND CURE RATE

Cure reaction begins with the mixing process. Initially, cure is evidenced by a gradual increase in viscosity, followed by gelation and conversion to a solid elastomer. Pot life is defined as the time required for viscosity to double after Parts A and B (base and curing agent) are mixed and is highly temperature and application dependent. Please refer to the data table.

## USEFUL TEMPERATURE RANGES

For most uses, silicone encapsulants should be operational over a temperature range of -45 to 200 °C (-49 to 392 °F) for long periods of time. However, at both the low- and high temperature ends of the spectrum, behavior of the materials and performance in particular applications can become more complex and require additional considerations and should be adequately tested for the particular end use environment. For low-temperature performance, thermal

cycling to conditions such as -55 °C (-67 °F) may be possible, but performance should be verified for your parts or assemblies. Factors that may influence performance are configuration and stress sensitivity of components, cooling rates and hold times, and prior temperature history. At the high-temperature end, the durability of the cured silicone elastomer is time and temperature dependent. As expected, the higher the temperature, the shorter the time the material will remain useable.

## COMPATIBILITY

Certain materials, chemicals, curing agents and plasticizers can inhibit the cure of addition cure gels. Most notable of these include: Organotin and other organometallic compounds, silicone rubber containing organotin catalyst, sulfur, polysulfides, polysulfones or other sulfur containing materials, unsaturated hydrocarbon plasticizers, and some solder flux residues. If a substrate or material is questionable with respect to potentially causing inhibition of cure, it is recommended that a small scale compatibility test be run to ascertain suitability in a given application. The presence of liquid or uncured product at the interface between the questionable substrate and the cured gel indicates incompatibility and inhibition of cure.

## REPAIRABILITY

In the manufacture of electrical/electronic devices it is often desirable to salvage or reclaim damaged or defective units. With most non-silicone rigid potting/encapsulating materials, removal or entry is difficult or impossible without causing excessive damage to internal circuitry. *Dow Corning* silicone encapsulants can be selectively removed with relative ease, depending on the chosen remove method and technique and repairs or changes accomplished, and the repaired area repotted in place with additional product. To remove silicone elastomers, simply cut with a sharp blade or knife and tear and remove

unwanted material from the area to be repaired. Sections of the adhered elastomer are best removed from substrates and circuitry by mechanical action such as scraping or rubbing and can be assisted by applying Dow Corning® brand OS Fluids to swell the elastomer. Before applying additional encapsulant to a repaired device, roughen the exposed surfaces of the cured encapsulant with an abrasive paper and rinse with a suitable solvent and dry. This will enhance adhesion and permit the repaired material to become an integral matrix with the existing encapsulant. Silicone prime coats are not recommended for adhering products to themselves.

## **PACKAGING INFORMATION**

Multiple packaging sizes are available for this product. Please contact your local distributor or Dow Corning representative for information on packaging size and availability.

## **USABLE LIFE AND STORAGE**

Shelf life is indicated by the “Use Before” date found on the product label. Refer to the product label for storage temperature requirements. Special precautions must be taken to prevent moisture from contacting these materials. Containers should be kept tightly closed and head or air space minimized. Partially filled containers should be purged with dry air or other gases, such as nitrogen. Exposure to moisture could reduce adhesion and cause bubbles to form. Encapsulant materials which contain higher levels of fillers that have been stored for long periods of time should typically be agitated or rolled prior to mixing to prevent separation and settle-out.

## **HANDLING PRECAUTIONS SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE**

**HANDLING, READ PRODUCT AND MATERIAL SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE MATERIAL SAFETY DATA SHEET IS AVAILABLE ON THE DOW CORNING WEB SITE AT DOW CORNING.COM, OR FROM YOUR DOW CORNING SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CORNING CUSTOMER SERVICE.**

## **LIMITATIONS**

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

## **HEALTH AND ENVIRONMENTAL INFORMATION**

To support Customers in their product safety needs, Dow Corning has an extensive Product Stewardship organization and a team of Product Safety and Regulatory Compliance (PS&RC) specialists available in each area.

For further information, please see our Web site, [dowcorning.com](http://dowcorning.com) or consult your local Dow Corning representative.

## **LIMITED WARRANTY INFORMATION – PLEASE READ CAREFULLY**

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